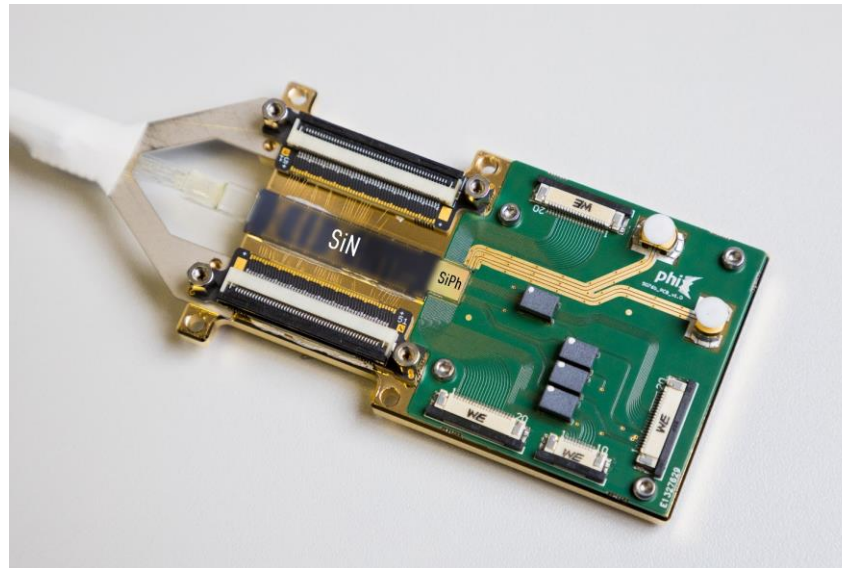
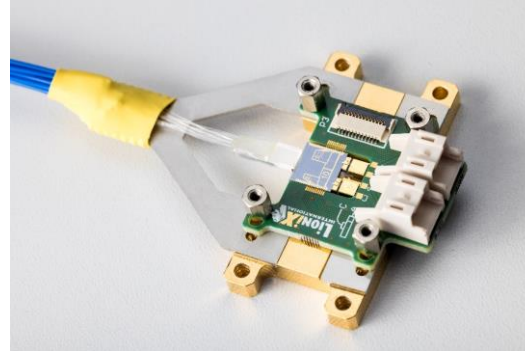


PHIX Photonics Assembly (from prototype to volume)

Competencies

- Die preparation
- Die alignment and bonding
- Electrical interfacing
- Thermal Packaging
- (Polarisation Maintaining) Fiber Arrays
- High Power
- Free Space packaging
- Hybrid assembly



Jeroen Duis CCO

